Arm-based (ARS) | 1U Rackmount | GPU Server

Supermicro ARS-121GL-NB2B-LCC

Arm-based (ARS) · 1U Rackmount · GPU Server · Liquid Cooling Server

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Form Factor **1U Rackmount**	CPU **NVIDIA Dual 72-core CPUs on a Grace™ CPU Superchip**
GPU **4 onboard GPUs**	Memory **Onboard Memory**

Key Features

- NVIDIA GB200 with 4 NVIDIA NVLink® (GB200 NVL4)
- Dual Nvidia 72-core Grace CPUs with liquid cooling
- Quad NVIDIA B200 GPUs with liquid cooling
- 960GB Onboard Memory
- Quad 800G ConnectX®-8 + 2 PCIe 5.0 x16 slots OR 4 PCIe 5.0 x16 slots
- 4 to 8 front hot-swap E1.S NVMe drive bays
- 48-52V DC Busbar

Form Factor	1U Rackmount
Platform	Arm-based (ARS)
CPU	Dual processor(s) NVIDIA Dual 72-core CPUs on a Grace™ CPU Superchip
Max GPU Count	4 onboard GPUs
Supported GPU	NVIDIA: B200 GPU on GB200 Grace Blackwell Superchip
Memory	Onboard Memory 960GB ECC LPDDR5X
Drive Bays	Default: Total 8 bays8 front hot-swap E1.S PCIe 5.0 x4 NVMe drive bays
Fans	8x 4cm heavy duty fans with optimal fan speed control
Power Supply	Power via Busbar (48-54V DC)

Full Specifications — ARS-121GL-NB2B-LCC

Product SKUs

Part numbers	ARS-121GL-NB2B-LCC

Motherboard

Motherboard	Super GPU-NVGB200-NVL4

Processor

CPU	Dual processor(s) NVIDIA Dual 72-core CPUs on a Grace™ CPU Superchip
Core Count	72C/72T; 114MB Cache per CPU
Note	Supports up to 300W TDP CPUs (Liquid Cooled)

GPU

Max GPU Count	4 onboard GPUs
Supported GPU	NVIDIA: B200 GPU on GB200 Grace Blackwell Superchip View GPU Options
CPU-GPU Interconnect	NVIDIA NVLink®-C2C
GPU-GPU Interconnect	Fifth-Generation NVIDIA NVLink™

System Memory

Memory	Onboard Memory 960GB ECC LPDDR5X

On-Board Devices

Network Connectivity	1 RJ45 2.5GbE with Intel® I210-AT (optional) 4 OSFP 800Gb InfiniBand with NVIDIA ConnectX®-8 SuperNIC (optional) 2 QSFP-DD 200Gb InfiniBand with NVIDIA® BlueField®-3 (optional) View AOC Options

Input / Output

LAN	1 RJ45 1 GbE Dedicated BMC LAN port (ASPEED AST2600)
USB	1 Type-A port (Front)
Video	1 Mini-DP port (Front)
TPM	1 TPM Onboard TPM & TPM Header

System BIOS

BIOS Type	AMI 64MB SPI Flash EEPROM

Management

Software	SuperCloud Composer® (SCC) SuperServer Automation Assistant (SAA) New!
Power configurations	Power-on mode for AC power recovery ACPI Power Management

Security

Hardware	Trusted Platform Module (TPM) 2.0
Features	Secure Firmware Updates

PC Health Monitoring

CPU	Monitors for CPU Cores, Chipset Voltages, Memory
Fan	Fans with tachometer monitoring Pulse Width Modulated (PWM) fan connectors Status monitor for speed control
Temperature	Monitoring for CPU and chassis environment Thermal Control for fan connectors

Certifications

Operating Systems	RHEL 9.6, Ubuntu 24.04.3 View all OS Compatibility and Certification Matrix

Chassis

Form Factor	1U Rackmount
Model	CSE-MG104TS-V01DP-NVL4

Dimensions and Weight

Height	1.7" (43.6 mm)
Width	17.26" (438.4 mm)
Depth	30.15" (766 mm)
Package	9.05" (H) x 24.8" (W) x 45.27" (D)
Weight	Gross Weight: 79.36 lbs (36 kg) Net Weight: 70.5 lbs (32 kg)
Available Color	Silver

Expansion Slots

PCI-Express (PCIe) Configuration	Default2 PCIe 5.0 x16 (in x16) FHFL slots Option A4 PCIe 5.0 x16 (in x16) FHFL slots View AOC Options

Drive Bays / Storage

Drive Bays Configuration	Default: Total 8 bays8 front hot-swap E1.S PCIe 5.0 x4 NVMe drive bays Option A: Total 4 bays4 front hot-swap E1.S PCIe 5.0 x4 NVMe drive bays View NVMe Options
M.2	1 M.2 PCIe 5.0 x4 NVMe slot (M-key 22110(default)) View M.2 Options

System Cooling

Fans	8x 4cm heavy duty fans with optimal fan speed control
Liquid Cooling	Direct to Chip (D2C) Cold Plate

Power Supply

Power	Power via Busbar (48-54V DC)
Power	Power via Busbar (48-54V DC)

Operating Environment

RoHS	RoHS Compliant
Environmental Spec.	Name: A2 Operating Temperature: 10°C to 35°C (50°F to 95°F) Non-operating Temperature: -30°C to 60°C (-40°F to 140°F) Operating Relative Humidity: 8% to 80% (max 21° DP; non-condensing) Non-operating Relative Humidity: 8% to 90% (max 38° DP; non-condensing)